Harnessing The Micro Revolution:

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A "Micro" Revolution for Spacecraft

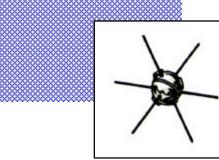
The Evolution of Manufacturing:

Custom
assembly of
non-standard
parts

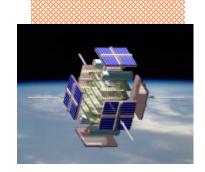
Custom assembly of standardized parts

Assembly-line manufacturing (serial)

Batch-processing (parallel)







Small Spacecraft: Launch Year:

Functional Elements:

Vanguard 1 1958

~100

DARPA PICOSAT 1999

~100,000

"Integrated" Satellites ~2005

~100,000,000



Microelectronics: The Evolution of a Revolution

Year:	Smallest Feature (microns)	Dynamic RAM:		Microprocessors:	
		Die Size (cm²)	Billions of Bits per Dice	Die Size (cm²)	Millions of Transistors per cm ²
1995	0.35	1.9	0.064	2.5	4
1998	0.25	2.8	0.256	3.0	7
2001	0.18	4.2	1	3.6	13
2004	0.13	6.4	4	4.3	25
2007	0.10	9.6	16	5.2	50
2010	0.07	14	64	6.2	90

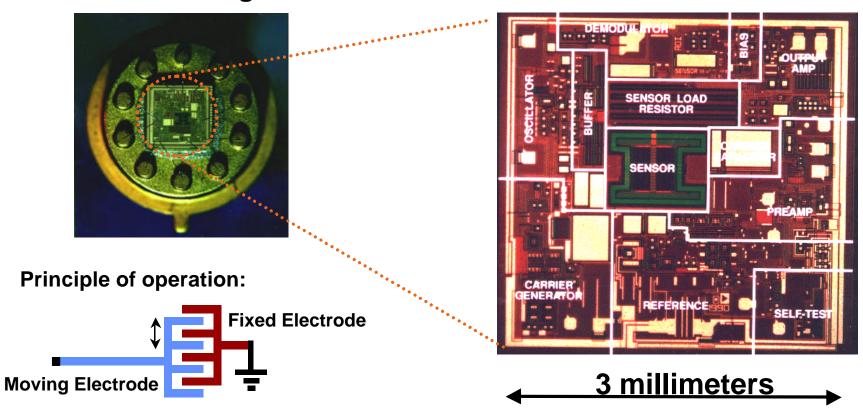
The microelectronics "revolution" continues along a predictable path

From "Technology 1996: Solid State", IEEE Spectrum, 33 #1, p. 51-55, January 1996



A REVOLUTION IN MECHANICAL CONSTRUCTION: MICROELECTROMECHANICAL SYSTEMS (MEMS)

Analog Devices ADXL50 Accelerometer





MEMS Accelerometers Monitored STS-93 Flight

Launch Silicon Designs 1010J & 1210J **Capacitive MEMS Accelerometers** 1800 1900 2000 2100 2200 2300 2400 Time (EDT, seconds) 0.1 **Z-Axis Acceleration (g's)**0.08
0.07
0.07
0.07 **Orbit Correction** Sensor **ASIC** 4200 4300 4400 4500 4600



Time (EDT, seconds)

Why MEMS Are An Enabling Technology

- You can simultaneously fabricate thousands of devices
 - Micron-to-millimeter scale machines
 - Coordinated primitive functions by multiple devices can produce complex functions (like a computer!)
- Integrated electronics can be co-manufactured
 - Increased signal-to-noise ratios for sensors due to reduced parasitic loads
 - You can produce "smart" sensors and actuators for high reliability
- Reduced size and power requirements for sensors
- Traditional off-chip components can be made on-chip
 - High frequency inductors, bandpass filters, etc.



Possible MEMS Insertion Into Spacecraft Systems:

Command and Control Systems:

-"MEMtronics" for ultra-radiation-hard and temperature-insensitive logic

Inertial Guidance Systems:

- Microgyros and microaccelerometers
 - Micromirrors and microoptics for FOGs (fiber optic gyros)

Attitude Determination and Control Systems:

- Micromachined sun and Earth sensors
- Micromachined magnetometers

Propulsion Systems:

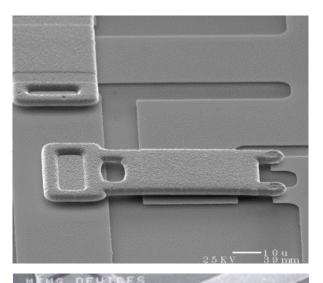
- Micromachined pressure and chemical sensors
- Arrays of single-shot thrusters ("digital propulsion")
 - Continuous or pulsed microthrusters

Communications and Radar Systems:

- Very high bandwidth, low power, low resistance rf switches
- Micromirrors and microoptics for laser communications



MEMS Switches: RF, Digital, or Analog

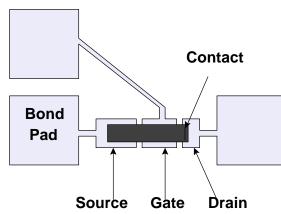


From:

P.M. Zavracky et al., "Micromechanical Switches Fabricated Using Nickel Surface Micromachining," *J. Microelectromechanical Systems*, **6** #1, March 1997

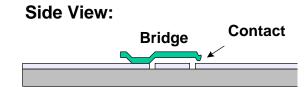
http://www.ece.neu.edu/eds nu/zavracky/mfl/programs/re lay/relay.html

Top View:



From:

Aerospace Corp.

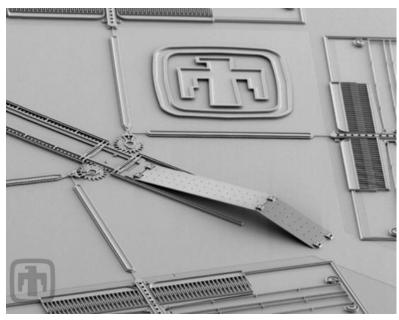


- Super radiation-hard,
- Wide operating temperature range
- Low insertion loss
- Wide bandwidth



Optical MEMS Devices for Possible Space Applications

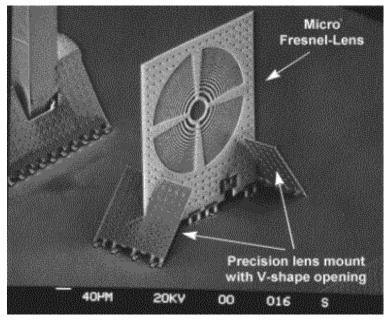
MEMS "Pop Up" Mirror (Sandia)



http://www.mdl.sandia.gov/micromachine/images6.html

See also: "Optics & MEMS" by S.J. Walker and D.J. Nagel, http://code6330.nrl.navy.mil/6336/moems.htm

MEMS "Pop Up" Lens (UCLA)



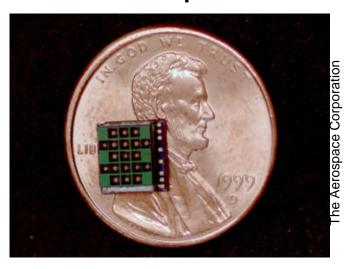
M.C. Wu, "Micromachining for Optical and Optoelectronic Systems," Proc. IEEE, Vol. 85, #11, Nov 1997; http://www.ee.ucla.edu/labs/laser/research/mot/1integrated.html



MEMS Thrusters and Components



15-Thruster "Chip" on STS-93

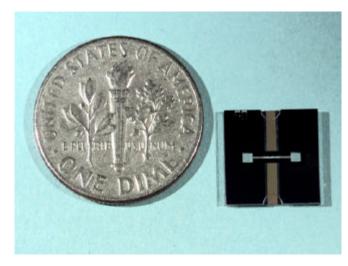


http://www.design.caltech.edu/micropropulsion/index.html

TRW, CalTech, and The Aerospace Corp.



Micro Isolation Valve



J. Mueller, S. Vago, D. Bame, D. Fitzgerald, and W. Tang," Proof-of-Concept Demonstration of a Micro-Isolation Valve," AIAA paper 99-2726, June 1999



21st Century Micro/Nano/Picosatellites

Highly-integrated designs

- More functional elements, fewer piece-parts
- Integrated diagnostics, self-test, and reconfiguration
- "Silicon satellites"; grams-to-kilograms in mass

Batch or assembly-line fabrication in large lots (>100)

- Virtual satellites, e.g., km-scale sparse aperture arrays
- Disposable satellites, e.g., satellite inspectors
- Dense constellations for continuous Earth coverage

• "Two-dimensional" satellites

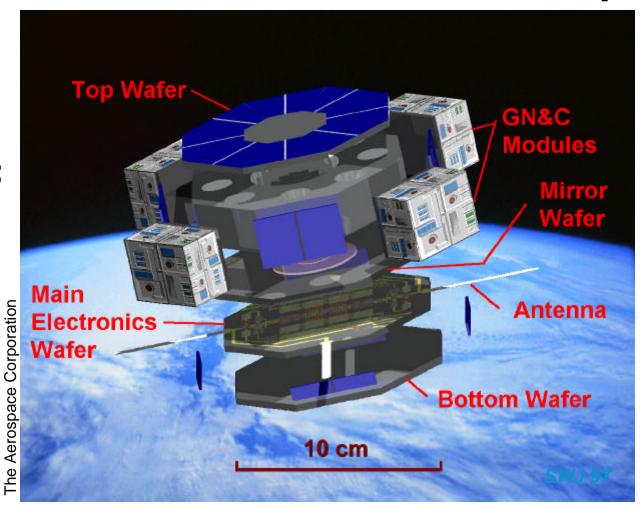
- Large aperture/weight ratios, e.g., TechSat-21



A Silicon Nanosatellite Concept

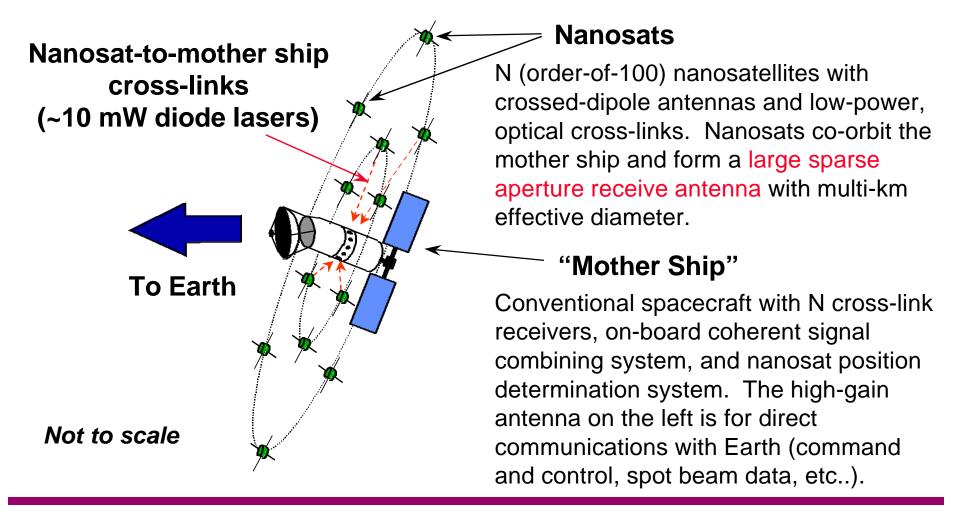
Silicon serves as:

Structure,
Radiation shield,
Thermal control,
Optical material,
MEMS substrate,
Electronic substrate





Nanosatellite Sparse Array Antenna Concept

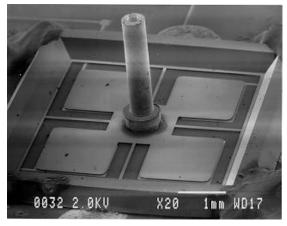


Relevant R&D Activity (U.S.)

MEMS for space applications

- AFRL, AFOSR, DARPA
- Sandia National Laboratories
- NASA-JPL, NASA-Glenn
- TRW, Draper Laboratories, Honeywell, Marotta Scientific, Hughes, Rockwell Science Center,...
- CalTech, MIT, U.C. Berkeley, UCLA, ...

NASA-JPL Microgyro



http://csmt.jpl.nasa.gov/mgyro.html

Integrated Micro/Nanospacecraft

- AFRL (TechSat-21)
- NASA-JPL (X-2000 Deep Space Systems Technology Program)
- Sandia (Nanosatellite)
- NASA-Goddard (Nanosatellites for magnetospheric mapping)



Summary:

- MEMS and microtechnology can enable small, lightweight, but sophisticated spacecraft for challenging missions
- Mass-produced, integrated spacecraft can enable new space missions such as km-scale virtual spacecraft
- Spacecraft design and space architectures may radically change during the next decade